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(71) Applicant: RENESAS TECHNOLOGY CORP

(72) Inventor: SATO MASAMICHI

SUGIYAMA MICHIAKI

TSUTSUMI YASUSHI

(54) SEMICONDUCTOR DEVICE AND  
MANUFACTURING METHOD THEREOF

ing pads to the border portion of the wiring board.

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(57) Abstract:

PROBLEM TO BE SOLVED: To miniaturize a semiconductor device from the view point of an arrangement of bonding pads and an installation form of feeder wiring for electrolytic plating.

SOLUTION: A first semiconductor chip (3) and second semiconductor chips (4, 5) are provided on a wiring board (2) having wiring layers of surface layer and an inner layer. The wiring board has first bonding pads (9Aa, 9Ab) wire bonded to the first semiconductor chip, second bonding pads (10a, 10b) wire bonded to the second semiconductor chips, first wiring for connecting between the first bonding pads and the second bonding pads, and second wiring led out from the second bonding pads to the border portion of the wiring board. The first and the second bonding pads are subjected to electrolytic plating, and the second wiring is utilized for the connection with the power supply for the electrolytic plating. The feeder wiring for the electrolytic plating is not required to be led out from the first bond-

